

TS-HINT: ENHANCING SEMICONDUCTOR TIME SERIES REGRESSION USING ATTENTION HINTS FROM LARGE LANGUAGE MODEL REASONING

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ABSTRACT

Existing data-driven methods rely on the extraction of static features from time series to approximate the material removal rate (MRR) of semiconductor manufacturing processes such as chemical mechanical polishing (CMP). However, this leads to a loss of temporal dynamics. Moreover, these methods require a large amount of data for effective training. In this paper, we propose *TS-Hint*, a Time Series Foundation Model (TSFM) framework, integrated with chain-of-thought reasoning which provides attention *hints* during training based on attention mechanism data and saliency data. Experimental results demonstrate the effectiveness of our model in limited data settings via few-shot learning and can learn directly from multivariate time series features.

Index Terms— Foundation model reasoning, Attention mechanism, Extrinsic regression, Semiconductor process, Multivariate time series

1. INTRODUCTION

With the increasing trend for the usage of computational electronic devices such as smartphones and computers, there is an increasing demand for semiconductor manufacturing processes. Among the critical processes of semiconductor manufacturing is chemical mechanical polishing (CMP) which requires planarization of the wafer thickness with precision in nanometers scale. However, the wafer thickness cannot be measured during the process and thus several heuristics and data-driven methods were used to approximate it and improve the efficiency of the polishing process. These methods range from traditional [1, 2], Physics-based [3], machine learning (ML) [4][5], and deep learning (DL) [6] models which rely heavily on techniques to extract static features from time series features.

There has been a recent trend in time series foundation models (TSFM) for downstream tasks. However, existing TSFMs do not have reasoning capabilities and most of them are applied to forecasting and classification, as per the author’s knowledge there is no work on TSFM for extrinsic

(sequence-to-one) regression task. TimeLLM [7] incorporates large language model (LLM) reasoning but is limited to forecasting. Several advances demonstrated the success of LLM reasoning, such as chain-of-thought, for time series model integration [8, 9]. We take motivation from recent works [10] that demonstrated the use of attention hint to improve the model performance in computer vision.

In this paper, we apply a novel TSFM with reasoning on semiconductor CMP process. TS-Hint achieved comparable performance with existing methods for the entire training dataset and demonstrated the benefits of the framework on limited data scenarios. The main contributions of this paper are summarized as follows:

- We propose a multivariate (19 features) time series foundation model for extrinsic regression, able to learn directly from raw time series features, and demonstrate its effectiveness in a semiconductor dataset.
- We enhance the time series regression model with in-context learning via LLM chain-of-thought reasoning using transformer attention scores and saliency maps.
- We demonstrate the model’s data efficiency with limited (15%) training data and further few-shot fine-tuning is incorporated with LLM to understand the reason of the prediction.

2. RELATED WORKS

The Deep Belief Network (DBN) model introduced in [11] has been reported as non-reproducible according to [6]. Nevertheless, [11] was the first to use the Preston equation as a benchmark to compare models for MRR prediction. The Physics-based approach proposed in [3] uses a Random Forest (RF) model to determine the unknown variables in their equation. However, such empirical models require specific features, such as particle density and wafer hardness, which are not measured in experiments, leaving heuristics and substitute features for their equations. An ensemble of three tree-based models, Gradient-Boosted Trees (GBT), RF, and Extremely Randomized Trees (ERT), proposed in [5] extracted

The authors would like to thank SUTD PhD Scholarship for funding the research and A*STAR for providing computational resources.

statistical features such as central moment, skewness, kurtosis, and standard deviation. The feature engineering approach proposed in [4] involves using features such as Stage, Wafer ID, Effective polishing time. However, these features are unconventional and include unique identifiers that may artificially correlate with the target MRR. The DL Autoencoder (AE) model proposed in [6] extracted statistical moments. However, these models depend on extracting static data from time series, resulting in loss of temporal information.

Recent works have integrated LLM reasoning to enhance time series performance [12, 13] and some specifically used chain-of-thought (CoT) reasoning for time series [8, 9]. However, [8] and [13] are limited to time series forecasting, while Chow et al. [9] only evaluated their framework on classification task and cannot be used as a benchmark for regression. LLM-TS Integrator [12] proposed sample reweighting by LLM reasoning but is highly dependent on the quality of textual description of time series. On the other hand, our proposed framework integrates LLM chain-of-thought reasoning by suggesting attention hints, which demonstrate the benefits of attention-based TSFMs over ML and DL models.

3. METHODOLOGY

3.1. Preliminaries

Material removal rate (MRR) cannot be measured during the actual chemical mechanical polishing (CMP) process. It is defined as the reduction in the thickness of the semiconductor wafer over time given by

$$\text{MRR} = \frac{\Delta \text{Thickness}}{\Delta \text{Polishing Time}} \quad (1)$$

Instead, the wafer thickness is measured before and after the process, where the duration of the polishing process (when to stop) is decided by heuristics and rules. The Preston equation [1] provides one of the earliest heuristics to estimate the MRR of the CMP process. It is given by

$$\text{MRR} = kPV \quad (2)$$

where P is the downward pressure applied to the wafer, V is the relative rotation speeds between the wafer and the polishing pad, and k is a constant.

3.2. Time Series Foundation Model

Time series foundation models (TSFM) have self-supervised capability, such that they can learn with minimal labeled samples and can be fine-tuned to several downstream tasks. Several TSFMs are limited to forecasting task [7], to univariate time series [14, 15], and to sequence-to-sequence tasks [16, 17, 18]. However, there are no existing TSFM that can

perform regression task. Among the TSFMs with classification capability, TimesNet [19] is not attention-based and Moment [20] has complex architecture compared to PatchTST [21] which is the backbone of our framework for regression task. We adapt TSFMs with classification capability with the following main modifications: (i) replace the classification head with a multi-layer perceptron regression head and change the loss function to mean squared error during training and; (ii) standardize the input time series with fixed length by resampling the input sequence via linear interpolation. PatchTST [21] converts time series into patches and passes to its transformer-based encoder where the attention score $A_h^{(i)}$ of sample i at attention head h can be retrieved using

$$A_h^{(i)} = \text{Softmax} \left(\frac{Q_h^{(i)} K_h^{(i)T}}{\sqrt{d_k}} \right) \quad (3)$$

where Q , K , and d_k are query, key, and attention head dimension respectively.

3.3. Chain-of-Thought Reasoning

Our proposed model, shown in Fig. 1, is a multivariate TSFM for regression enhanced by the LLM chain-of-thought reasoning. Chain-of-thought in the form of [prompt, think, think,..., answer] improves the factuality of LLM reasoning by sequential thinking before answering, thereby reducing hallucination.

Attention Maps. Attention scores reveal where the model focuses, and by providing attention hints during training, the model learns to focus on more important parts of the input. It is similar to knowledge distillation from pretrained model to the model being fine-tuned. To obtain attention insights, we calculate the average attention map from the top k , here $k = 5$, best samples from the pretrained model. The attention hint $H^{(i)}$ for sample i is reshaped to that of the attention layer score so that the attention score $\hat{A}_h^{(i)}$ in Eq. 3 becomes

$$\hat{A}_h^{(i)} = A_h^{(i)} + \lambda H^{(i)} \quad (4)$$

where λ controls the model training sensitivity to attention hint H at head h .

Saliency Maps. Since TSFM self-attention is calculated only per feature, due to channel independence, we cannot compare the attention scores between features. To obtain insights on feature importance, we calculate the average saliency of the top k , here $k = 5$, best samples from pretrained model. The calculated saliency map S reveals important features C and timesteps T by calculating the gradient of the output $f(x)$ with respect to the input x .

$$S(x) = \left| \frac{\partial f(x)}{\partial x} \right| \in \mathbb{R}^{C \times T} \quad (5)$$

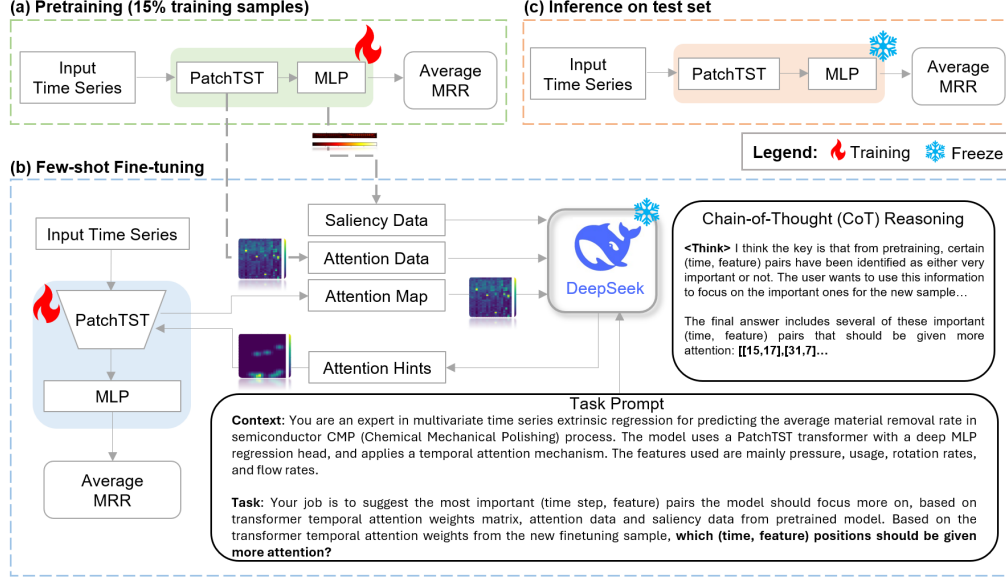


Fig. 1. Overview of TS-Hint architecture shows (a) pretraining on 15% training data, (b) few-shot fine-tuning one sample at a time enhanced by LLM chain-of-thought reasoning, and (c) inference on the test set. Dashed arrow lines indicate the attention data and saliency data retrieved from the pretrained model once.

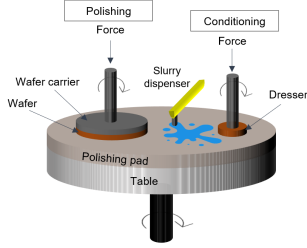


Fig. 2. Chemical mechanical polishing setup.

During fine-tuning, the model parameters are updated to minimize the loss function. The saliency maps were generated using the Saliency attribution method of the Captum library which implements a gradient-based approach [22].

4. EXPERIMENTS

4.1. Dataset

We benchmarked our model using the 2016 Prognostics and Health Management (PHM) dataset [23] on semiconductor CMP process, for which the physical setup is shown in Fig. 2. The dataset includes static features such as Stage, Machine ID, Wafer ID, and Chamber ID but we only used the 19 time series features, including pressure, usage, rotation rates, and flow rates, as input to the TSFM. Our model only uses the chamber ID to distinguish the mode for which the wafer sample was polished, as shown in Table 1.

Table 1. The Chamber ID (static) provides the information of the mode of each CMP run.

Mode	Chamber	Average MRR	Train	Test
Low-speed	4,5,6	55-110 nm/min	1613	364
High-speed	1,2,3	140-170 nm/min	351	73

4.2. Performance Evaluation

Experimental Settings. We ran the numerical experiments on a computer workstation with a NVIDIA 16 GB GPU GeForce RTX 4080 SUPER. DeepSeek-R1 14B via Ollama takes up to 12 GB in GPU memory during reasoning. The regression head has six hidden layers [1024,512,256,128,64,32] and ReLU activation functions. For training, we used Adam Optimizer with an initial learning rate of 0.001 and MSE loss function. For fine-tuning, the learning rate is reduced to 0.0001.

Table 2 demonstrates the effectiveness of our framework in limited data settings. Since there is no pretrained TSFM for the regression task, we pretrain using 15% training samples. Starting with the pretrained (0-shot) performance 8.86 RMSE, the model improves the regression performance with few-shot (5-shot) learning down to 8.20 RMSE. To make par comparison with existing methods, we also ran the proposed TS-Hint framework using full training data and compared with existing methods such as Preston [11], Physics-based ML [3], GBDT [5], RF [4], Autoencoder [6], TimesNet [19], and Moment [20]. We evaluated the models using common regression metrics such as the root mean squared error

Table 2. Few-shot fine-tuning performance on the test set.

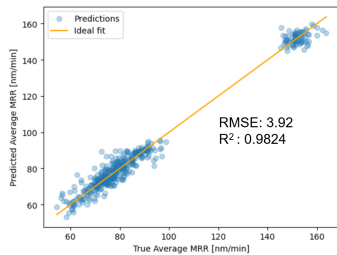
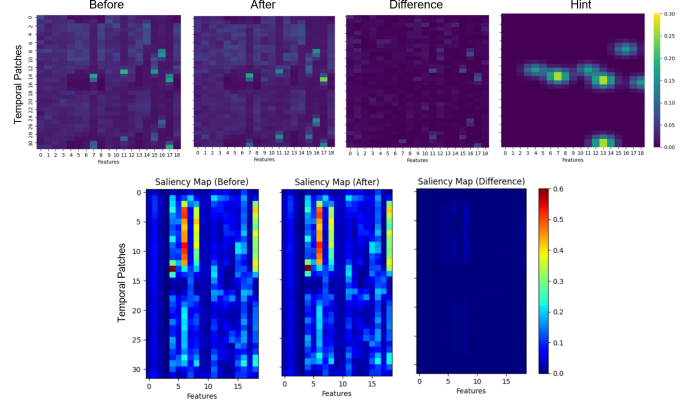
N-shot Learning	RMSE	R ²
0-shot	8.8678	0.9100
1-shot	8.6903	0.9135
2-shot	8.9478	0.9083
3-shot	8.6956	0.9134
4-shot	8.4221	0.9188
5-shot	8.2022	0.9230

Table 3. RMSE scores of benchmark models on the test set using full training data.

Type	Model	RMSE
Traditional,	Preston	29.5
Hybrid	Phys-inf ML	15.77
ML	GBDT	4.64
	RF	2.72
DL	AE	4.77
	Moment	6.17
TSFM	TimesNet	4.21
	TS-Hint (Ours)	3.92

(RMSE) and the coefficient of determination (R^2). Table 3 shows that TS-Hint with 3.92 RMSE outperformed all benchmark models except for the Random Forest [4] which achieved 2.72 RMSE. We tried reproducing [4] and achieved 2.98 RMSE. However, removing the "STAGE" static feature, degrades the performance to 3.57 RMSE. TS-Hint can be competitive in multivariate time series extrinsic regression against ML and DL models only by using time series features. Fig. 3 shows the scatter plot of the regression fit illustrating that the model tends to overpredict the target.

Reasoning Effectiveness. Fig. 4 shows the attention maps before and after 1-shot fine-tuning, the attention hint suggested by the LLM chain-of-thought reasoning, and the saliency maps before and after 1-shot fine-tuning. The absolute differences between the before and after are also shown in Fig 4 which illustrates where the adjustments in attention and gradient attribution occurred. For example, the attention shifted to features 15-17, Stage rotation, Head rotation, and Dressing water status, and the gradient attribution is slightly

**Fig. 3.** Scatter plot of true vs predicted average MRR of the TS-Hint for regression using full train data.**Fig. 4.** Before, after, and absolute difference for 1-shot fine-tuning (top) attention maps and attention hint and (bottom) saliency maps.

reduced in feature 8, Ripple air bag pressure. The model's reasoning is backed by data-driven insights based on what has worked well in the past and what is currently important. For example, the LLM considers a handpicked combination of the important timesteps from the given attention insights and the important features from the given saliency insights. Incorporating the attention hint during few-shot fine-tuning results in a decrease in training loss in most cases. For example, after 1-shot fine-tuning, the training loss decreased from 0.7710 to 0.6085. This improvement did not result in overfitting the train set as the model performance also improved in the test set shown in Table 2.

5. CONCLUSION

We developed a multivariate time series foundation model enhanced by LLM chain-of-thought reasoning. We demonstrated the effectiveness of our framework on limited data scenarios via a few-shot fine-tuning. Our model achieved 3.92 RMSE which is comparable to the top regression models in CMP PHM dataset showing the model's ability to learn directly from time series data. We hope that our work provides a stepping stone for LLM reasoning integration utilizing attention scores and saliency weights. Despite this, we recognize that LLMs still struggle to understand time series data and high-dimensional matrix since LLMs reason more symbolically than numerically. Unfortunately, integrating LLM reasoning during training makes training process much longer and computationally expensive. For future work, we plan to extend LLM reasoning with self-reflection reasoning and letting the LLM tune certain parameters (number of hints, hint weights, and hint smoothen kernel size) when applying attention hints.

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